

# 1 Characteristics

**Table 1. Absolute maximum ratings ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ )**

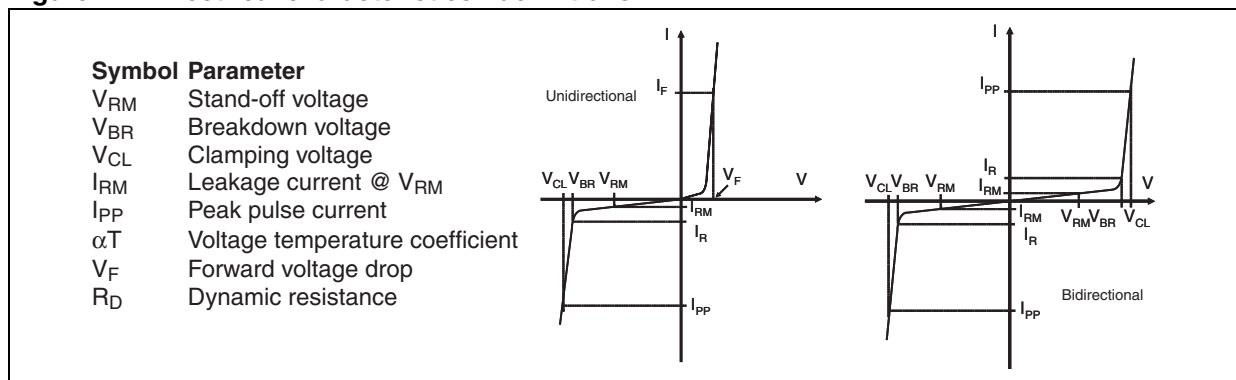
Symbol	Parameter	Value	Unit
$P_{PP}$	Peak pulse power dissipation <sup>(1)</sup>	$T_{j\text{ initial}} = T_{amb}$ 1500	W
$T_{stg}$	Storage temperature range	-65 to + 150	$^{\circ}\text{C}$
$T_j$	Operating junction temperature range	-55 to + 150	$^{\circ}\text{C}$
$T_L$	Maximum lead temperature for soldering during 10 s.	260	$^{\circ}\text{C}$

1. For a surge greater than the maximum values, the diode will fail in short-circuit.

**Table 2. Thermal parameter**

Symbol	Parameter	Value	Unit
$R_{th(j-l)}$	Junction to leads	15	$^{\circ}\text{C/W}$
$R_{th(j-a)}$	Junction to ambient on printed circuit on recommended pad layout	90	$^{\circ}\text{C/W}$

**Figure 1. Electrical characteristics - definitions**



**Figure 2. Pulse definition for electrical characteristics**

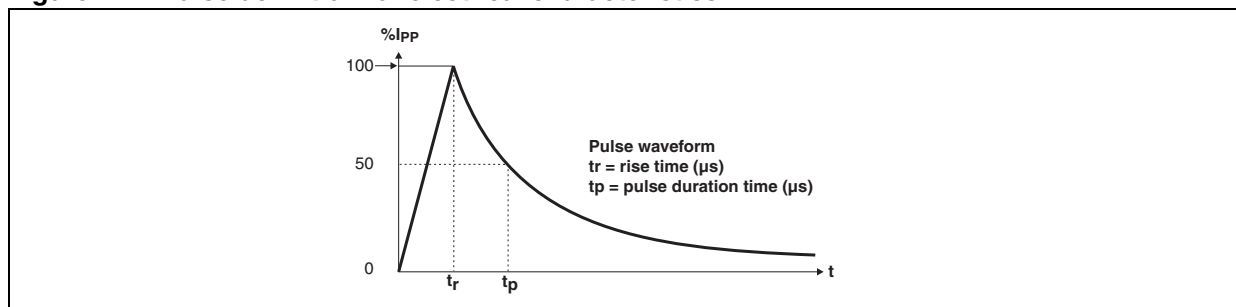


Table 3. Electrical characteristics, parameter values ( $T_{amb} = 25\text{ °C}$ )

Order code	$I_{RM} \text{ max}@V_{RM}$		$V_{BR} @I_R^{(1)}$				$V_{CL} @I_{PP}$ 10/1000 $\mu\text{s}$		$R_D$ 10/1000 $\mu\text{s}$	$V_{CL} @I_{PP}$ 8/20 $\mu\text{s}$		$R_D$ 8/20 $\mu\text{s}$	$\alpha T^{(2)}$	
	25 °C	85 °C	min	typ	max	max			max			max		
	$\mu\text{A}$		V	V		mA	V <sup>(3)</sup>	A <sup>(4)</sup>	$\Omega$	V <sup>(3)</sup>	A <sup>(4)</sup>	$\Omega$	10-4/ °C	
SM15T6V8A/CA	500	2000	5.8	6.45	6.8	7.14	10	10.5	143	0.023	13.4	746	0.008	5.7
SM15T7V5A/CA	250	1000	6.4	7.13	7.5	7.88	10	11.3	132	0.026	14.5	690	0.010	6.1
SM15T10A/CA	10	50	8.55	9.5	10	10.5	1	14.5	103	0.039	18.6	538	0.015	7.3
SM15T12A/CA	0.2	1	10.2	11.4	12	12.6	1	16.7	90	0.046	21.7	461	0.020	7.8
SM15T15A/CA	0.2	1	12.8	14.3	15	15.8	1	21.2	71	0.076	27.2	368	0.031	8.4
SM15T18A/CA	0.2	1	15.3	17.1	18	18.9	1	25.2	59.5	0.106	32.5	308	0.044	8.8
SM15T22A/CA	0.2	1	18.8	20.9	22	23.1	1	30.6	49	0.153	39.3	254	0.064	9.2
SM15T24A/CA	0.2	1	20.5	22.8	24	25.2	1	33.2	45	0.178	42.8	234	0.075	9.4
SM15T27A/CA	0.2	1	23.1	25.7	27	28.4	1	37.5	40	0.228	48.3	207	0.096	9.6
SM15T30A/CA	0.2	1	25.6	28.5	30	31.5	1	41.5	36	0.278	53.5	187	0.12	9.7
SM15T33A/CA	0.2	1	28.2	31.4	33	34.7	1	45.7	33	0.333	59.0	169	0.14	9.8
SM15T36A/CA	0.2	1	30.8	34.2	36	37.8	1	49.9	30	0.403	64.3	156	0.17	9.9
SM15T39A/CA	0.2	1	33.3	37.1	39	41.0	1	53.9	28	0.461	69.7	143	0.20	10.0
SM15T68A/CA	0.2	1	58.1	64.6	68	71.4	1	92	16.3	1.26	121	83	0.60	10.4
SM15T75A/CA	0.2	1	64.1	71.3	75	78.8	1	103	14.6	1.66	134	75	0.74	10.5
SM15T100A/CA	0.2	1	85.5	95.0	100	105	1	137	11	2.91	178	56	1.30	10.6
SM15T150A/CA	0.2	1	128	143	150	158	1	207	7.2	6.81	265	38	2.82	10.8
SM15T200A/CA	0.2	1	171	190	200	210	1	274	5.5	11.6	353	28	5.11	10.8
SM15T220A/CA	0.2	1	188	209	220	231	1	328	4.6	21.1	388	26	6.04	10.8

1. Pulse test :  $t_p < 50\text{ ms}$

2. To calculate  $V_{BR}$  versus junction temperature, use the following formula:  $V_{BR} @ T_J = V_{BR} @ 25\text{ °C} \times (1 + \alpha T \times (T_J - 25))$ .

3. To calculate maximum clamping voltage at other surge level, use the following formula:  $V_{CL} = R_D \times I_{PP} + V_{BRmax}$ .

4. Surge capability given for both directions for unidirectional and bidirectional types.

Figure 3. Peak pulse power dissipation versus initial junction temperature (printed circuit board)

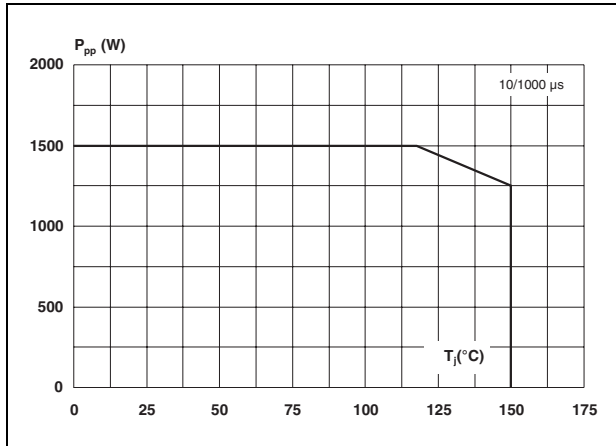


Figure 4. Peak pulse power versus exponential pulse duration

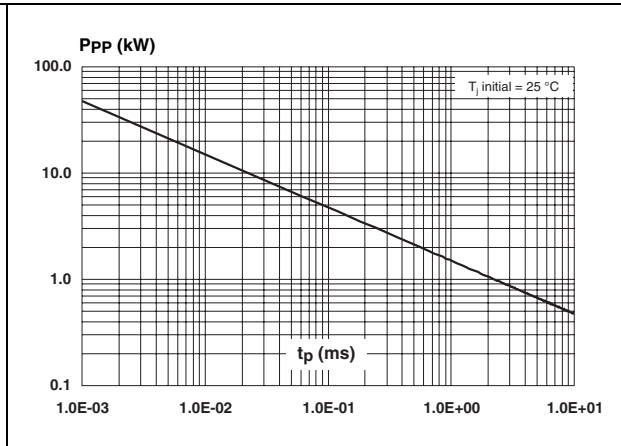


Figure 5. Clamping voltage versus peak pulse current (maximum values)

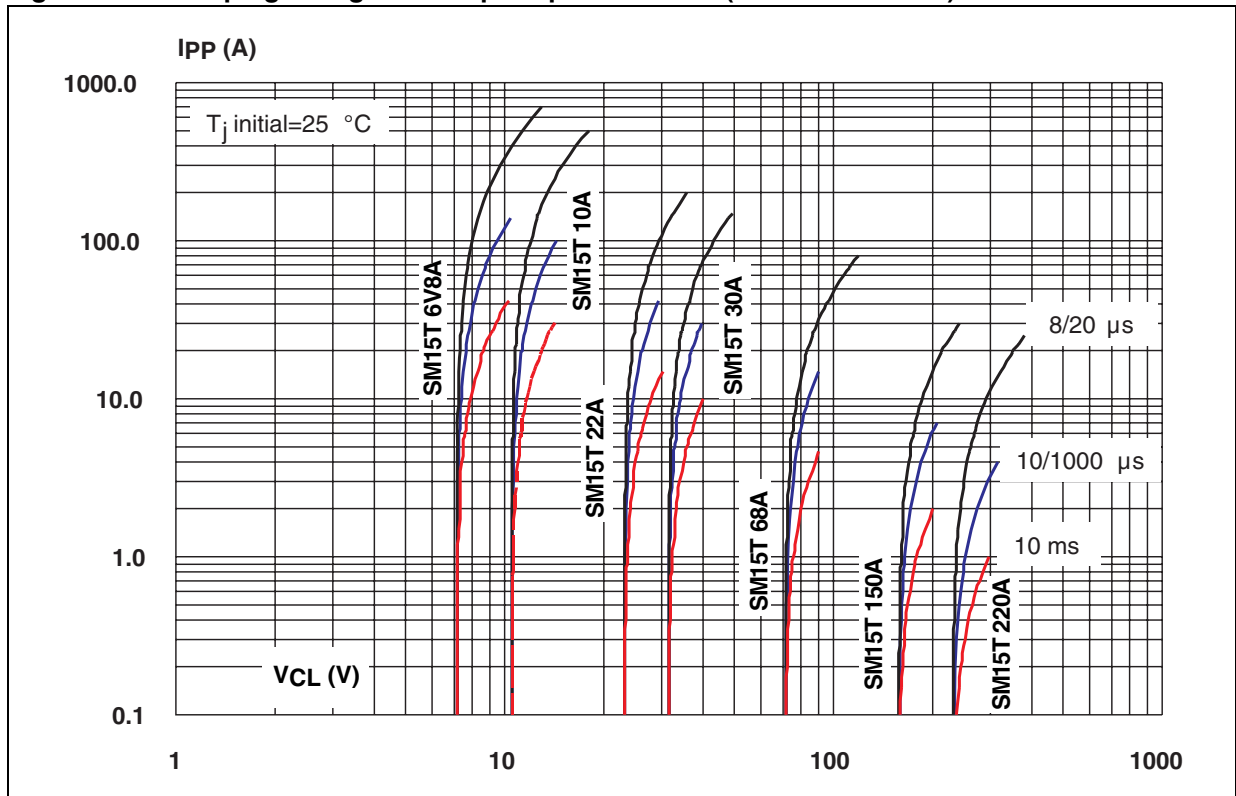


Figure 6. Capacitance versus reverse applied voltage (typical values, SM15TxxA)

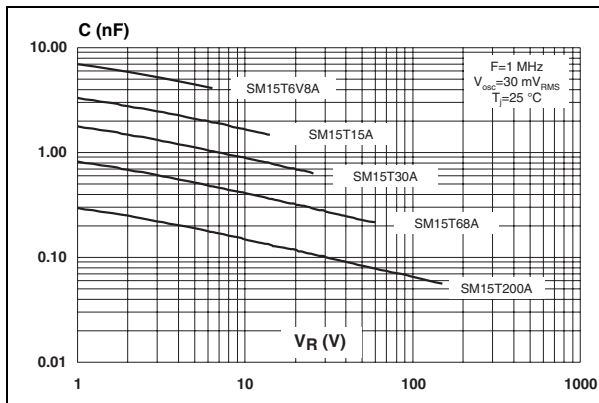


Figure 7. Capacitance versus reverse applied voltage (typical values, SM15TxxCA)

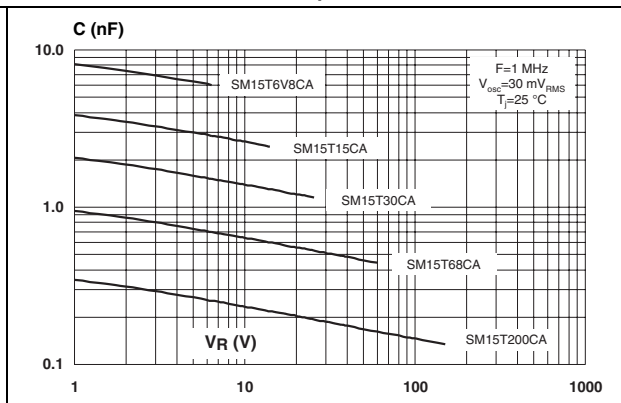


Figure 8. Peak forward voltage drop versus forward current (typical values)

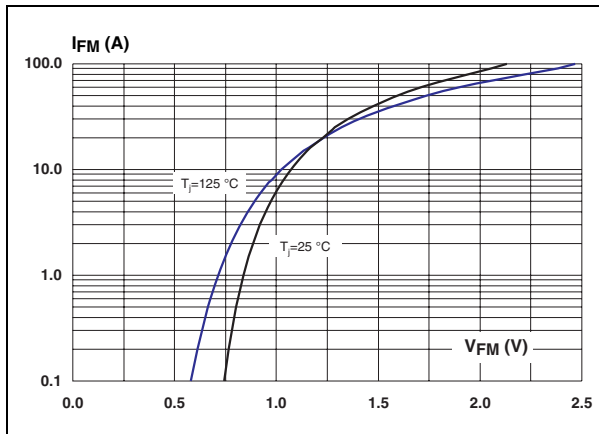


Figure 9. Relative variation of thermal impedance junction to ambient versus pulse duration

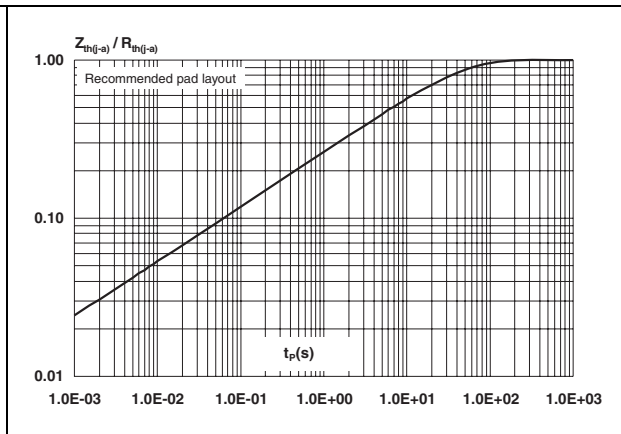


Figure 10. Thermal resistance junction to ambient versus copper surface under each lead

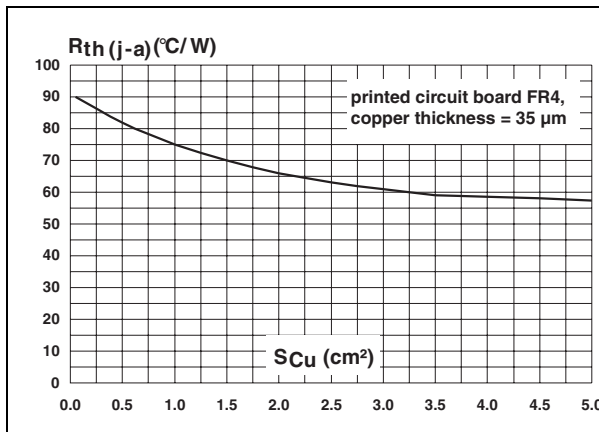
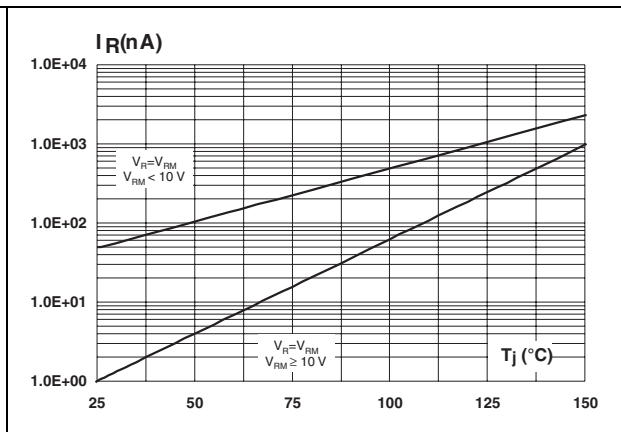
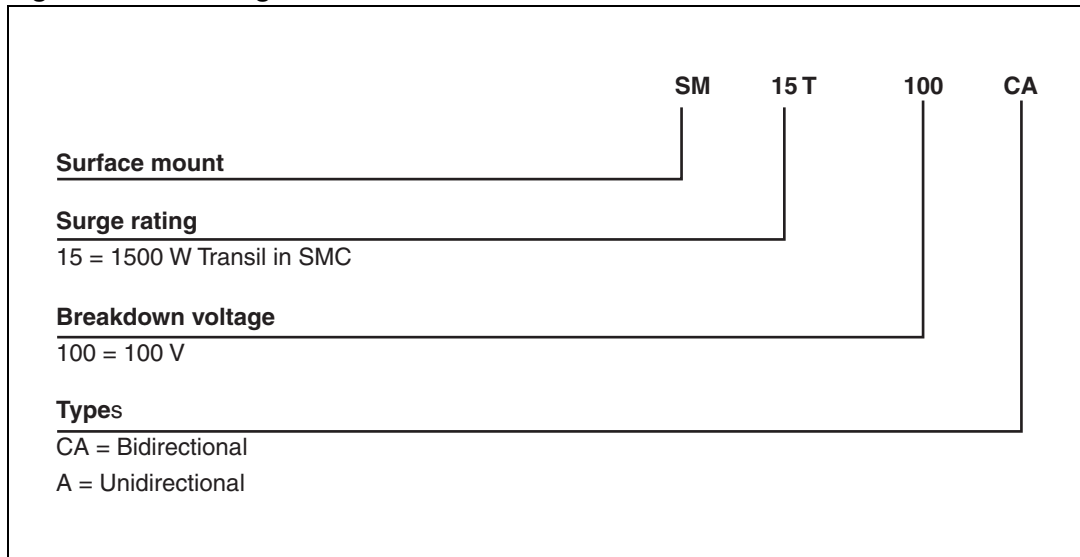


Figure 11. Leakage current versus junction temperature (typical values)



## 2 Ordering information scheme

Figure 12. Ordering information scheme



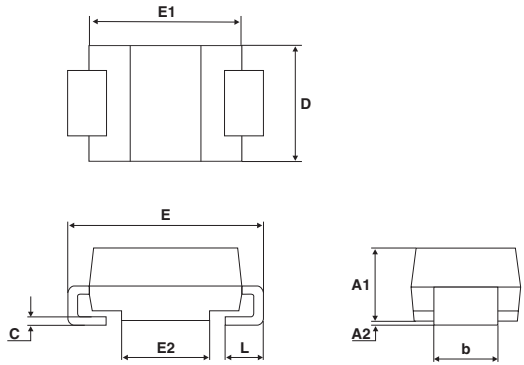
### 3 Package information

- Case: JEDEC DO-214AB molded plastic over planar junction
- Terminals: solder plated, solderable as per MIL-STD-750, Method 2026
- Polarity: for unidirectional types the band indicates cathode
- Flammability: epoxy is rated UL 94, V0
- RoHS package

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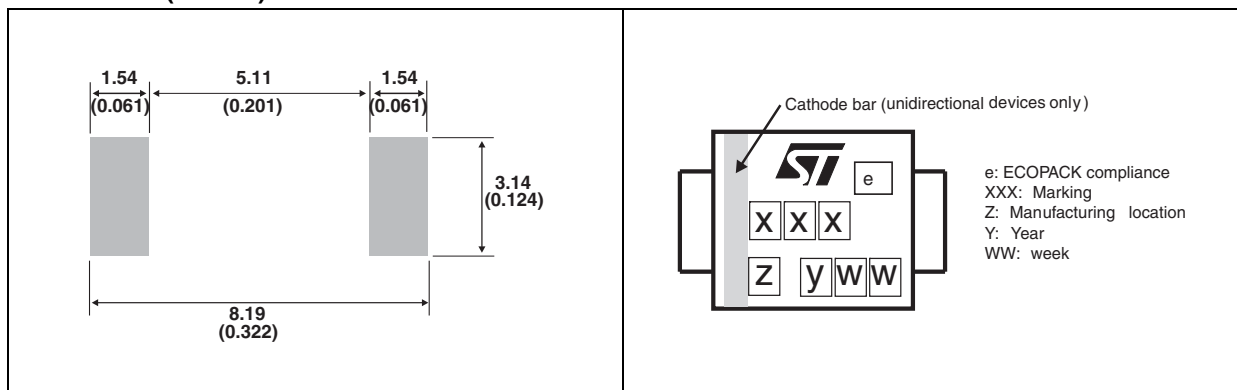
**Table 4. SMC dimensions**

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	2.90	3.20	0.114	0.126
c	0.15	0.40	0.006	0.016
D	5.55	6.25	0.218	0.246
E	7.75	8.15	0.305	0.321
E1	6.60	7.15	0.260	0.281
E2	4.40	4.70	0.173	0.185
L	0.75	1.50	0.030	0.059



**Figure 13. SMC footprint dimensions in mm (inches)**

**Figure 14. Marking layout<sup>(1)</sup>**



1. Marking layout can vary according to assembly location.

Table 5. Marking

Order code	Marking	Order code	Marking
SM15T6V8A	MDE	SM15T6V8CA	BDE
SM15T7V5A	MDG	SM15T7V5CA	BDG
SM15T10A	MDP	SM15T10CA	BDP
SM15T12A	MDT	SM15T12CA	BDT
SM15T15A	MDX	SM15T15CA	BDX
SM15T18A	MEE	SM15T18CA	BEE
SM15T22A	MEK	SM15T22CA	BEK
SM15T24A	MEM	SM15T24CA	BEM
SM15T27A	MEP	SM15T27CA	BEP
SM15T30A	MER	SM15T30CA	BER
SM15T33A	MET	SM15T33CA	BET
SM15T36A	MEV	SM15T36CA	BEV
SM15T39A	MEX	SM15T39CA	BEX
SM15T68A	MFP	SM15T68CA	BFP
SM15T75A	MFO	SM15T75CA	BFO
SM15T100A	MFX	SM15T100CA	BFX
SM15T150A	MGK	SM15T150CA	BGK
SM15T200A	MGV	SM15T200CA	BGV
SM15T220A	MGX	SM15T220CA	BGX

## 4 Ordering information

**Table 6. Ordering information**

Order code	Marking	Package	Weight	Base qty	Delivery mode
SM15TxxxA/CA <sup>(1)</sup>	See <a href="#">Table 5 on page 8</a>	SMC	0.25 g	2500	Tape and reel

1. Where xxx is nominal value of  $V_{BR}$  and A or CA indicates unidirectional or bidirectional version. See [Table 3](#) for list of available devices and their order codes

## 5 Revision history

**Table 7. Document revision history**

Date	Revision	Description of changes
September-2001	3B	Last issue
19-Feb-2007	4	Peak pulse power <a href="#">Figure 4 on page 4</a> updated.
04-Feb-2009	5	Updated ECOPACK statement. Added $R_D$ columns in <a href="#">Table 3</a> . Updated characteristic curves, <a href="#">Figure 3</a> to <a href="#">Figure 11</a> .
17-Sep-2009	6	Document updated for low leakage current.



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